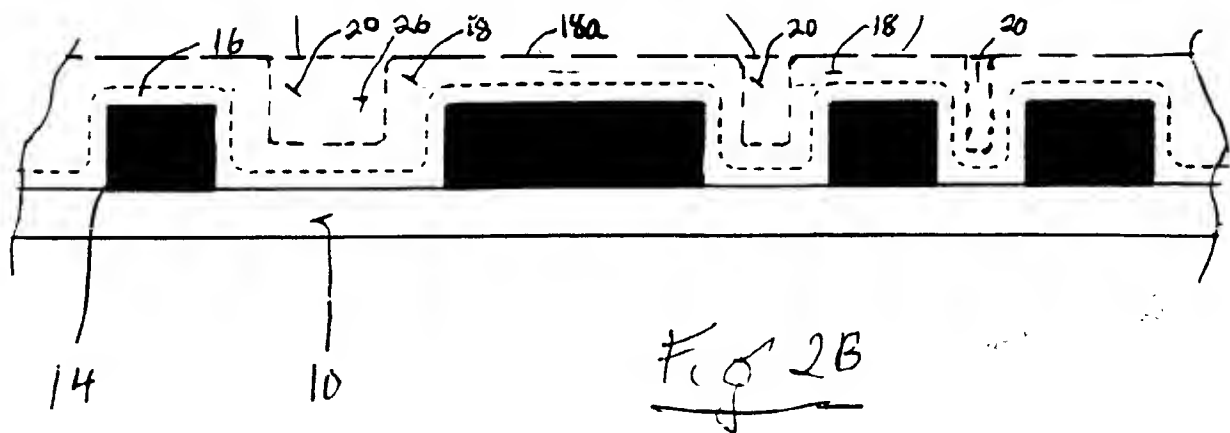


**Figure : After deposition of gapfilling polymer and CMP**



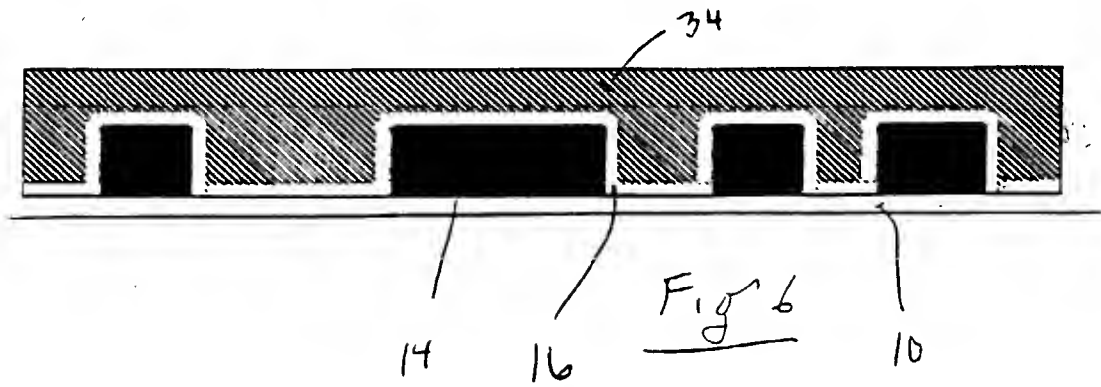
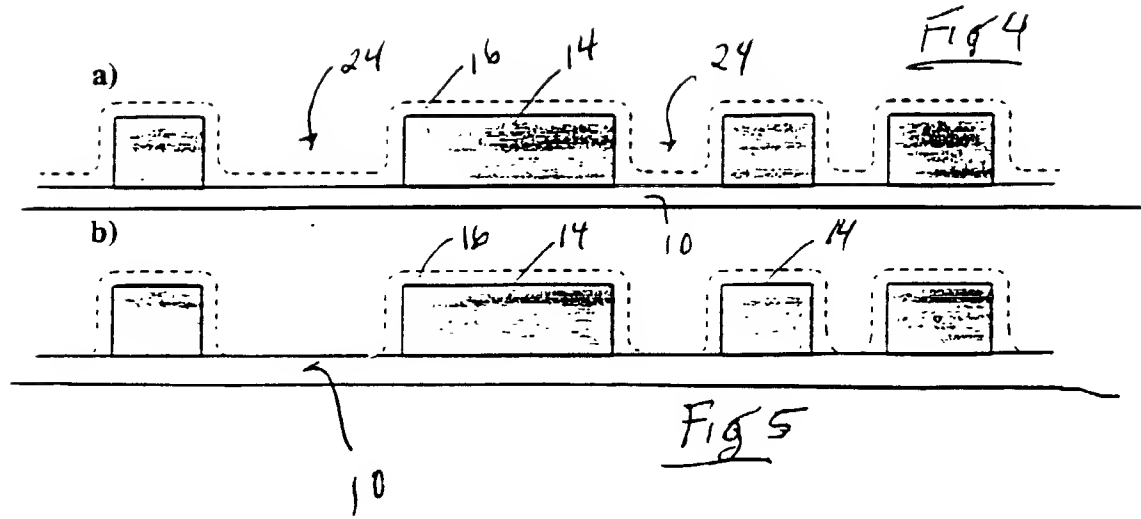


Fig 7

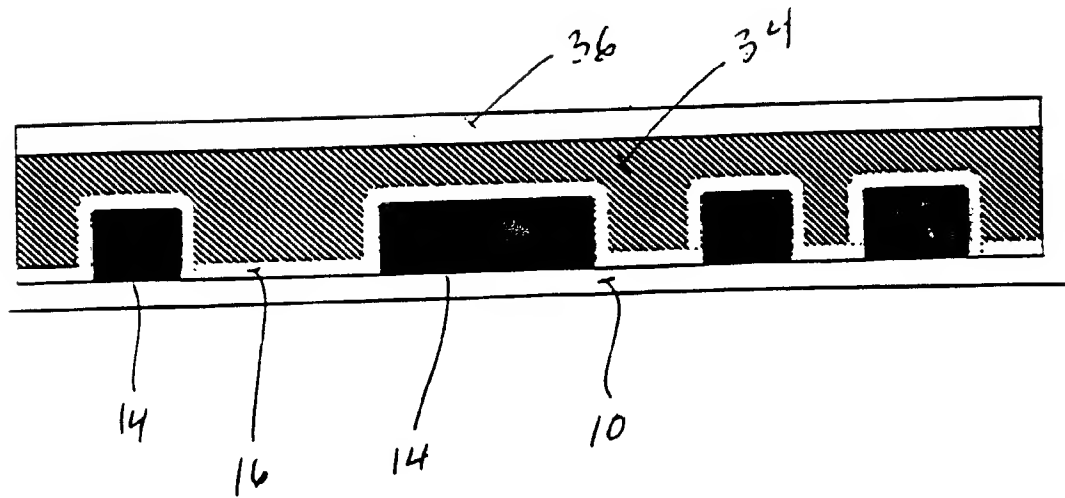


Fig 8

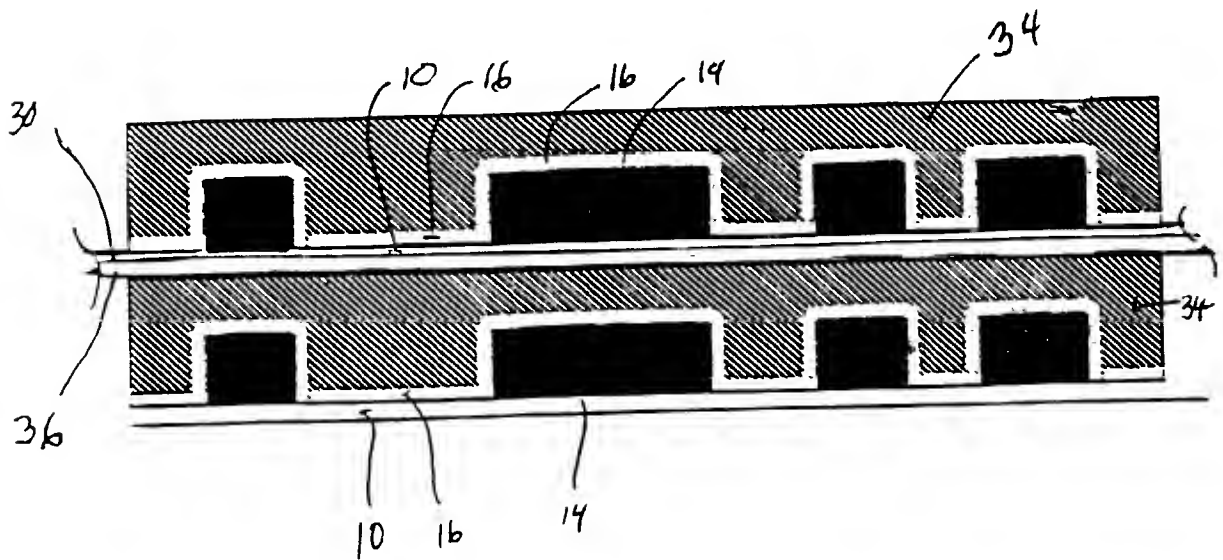


Fig 9

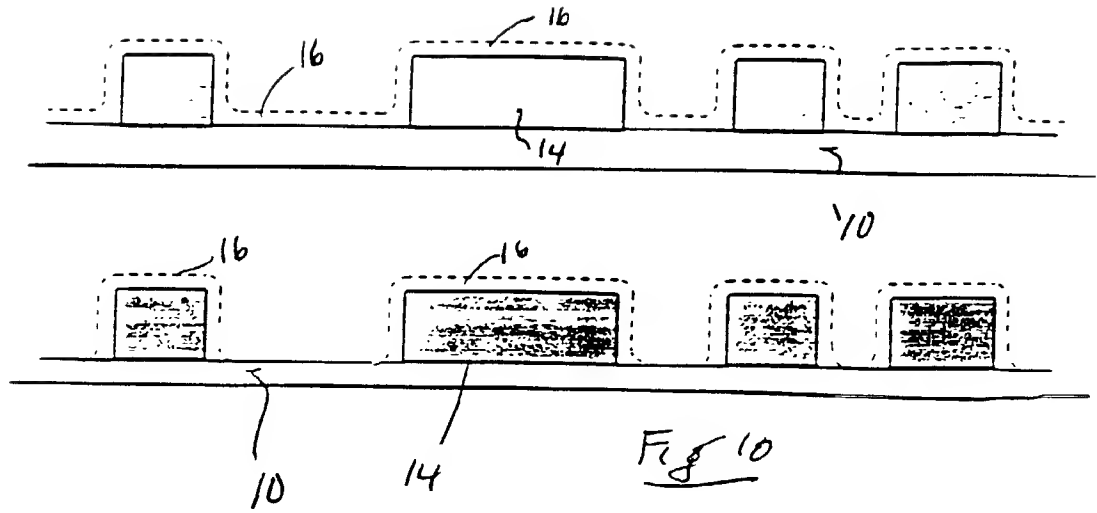


Fig 10

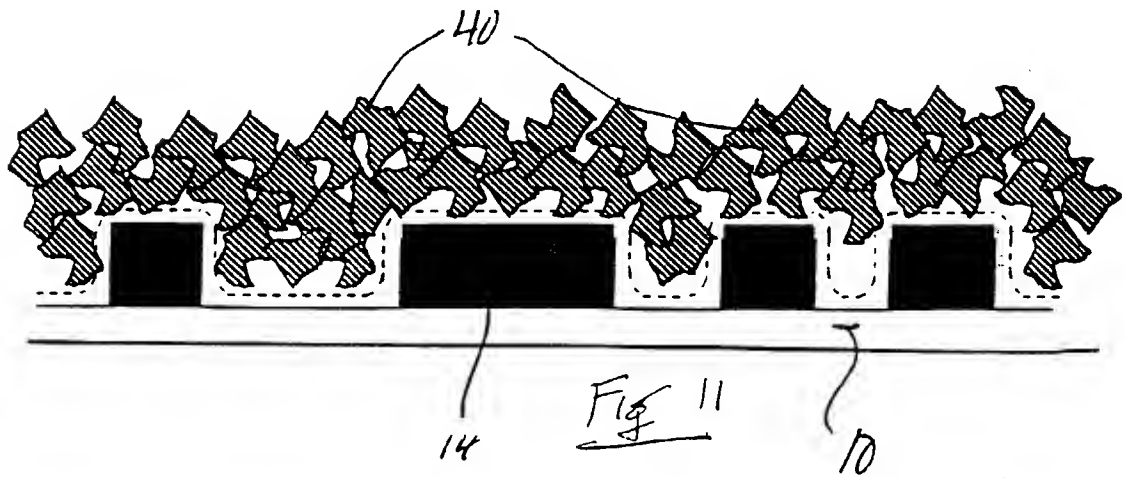




Fig 14

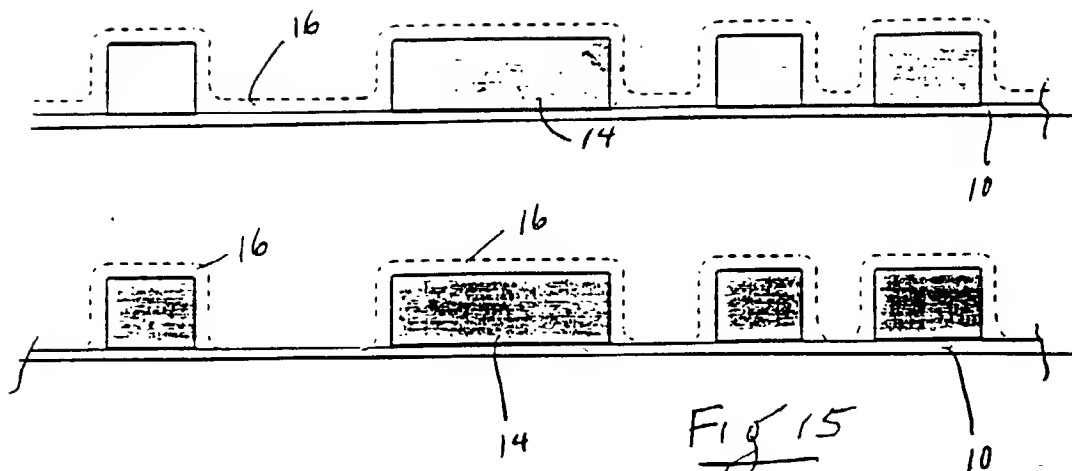
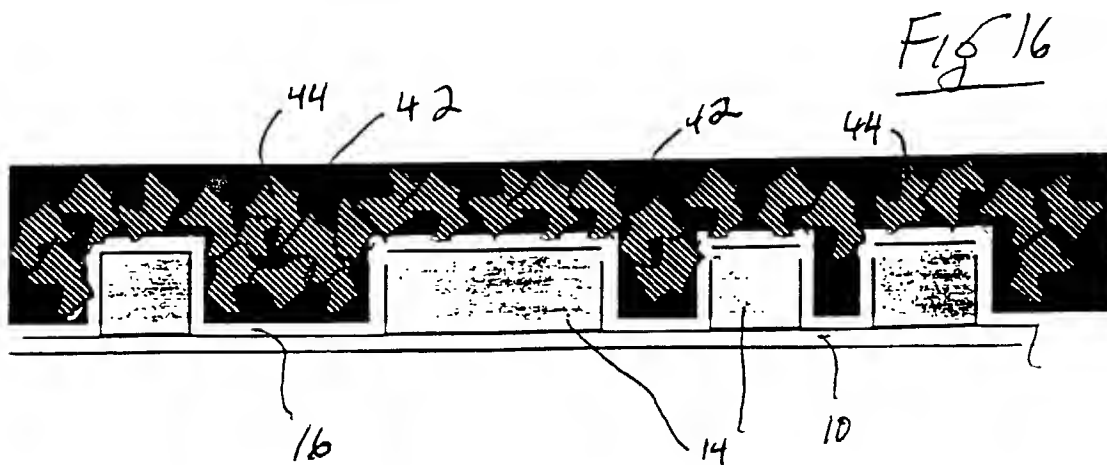


Fig 15



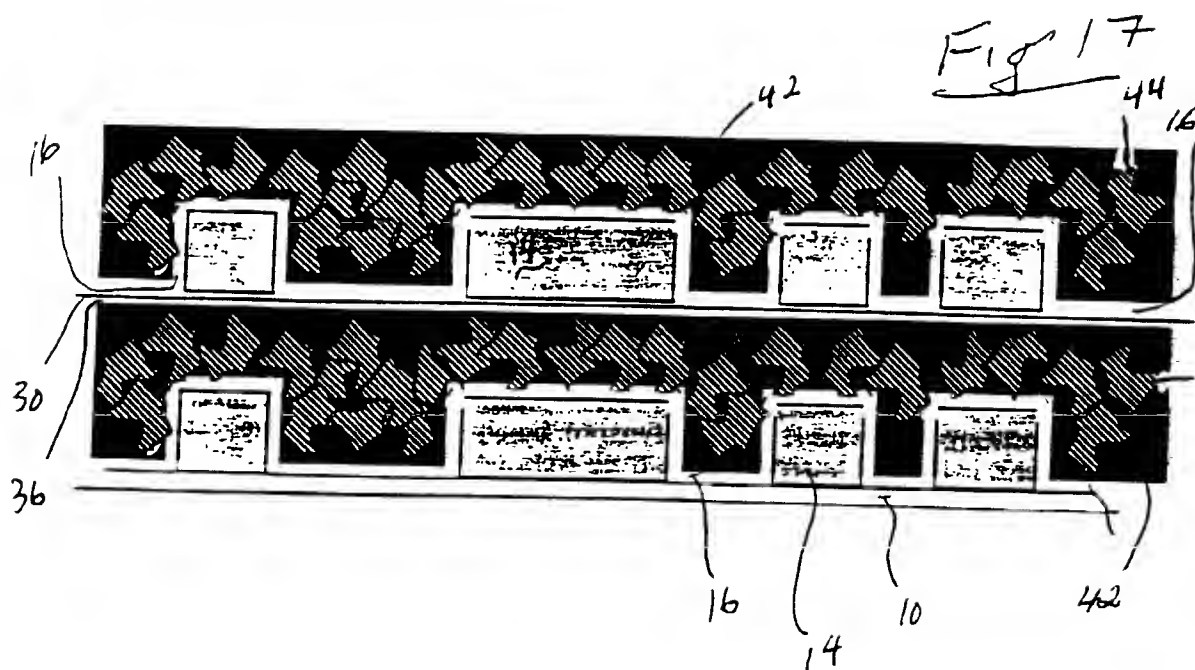
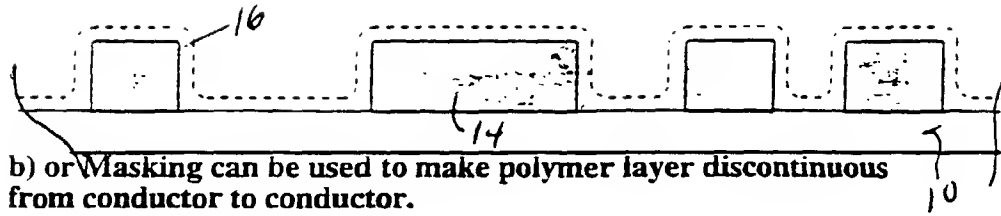




Fig 18



b) or Masking can be used to make polymer layer discontinuous from conductor to conductor.

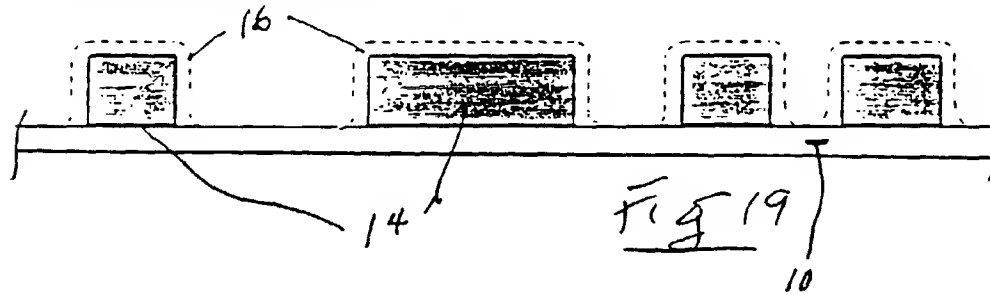


Fig 19

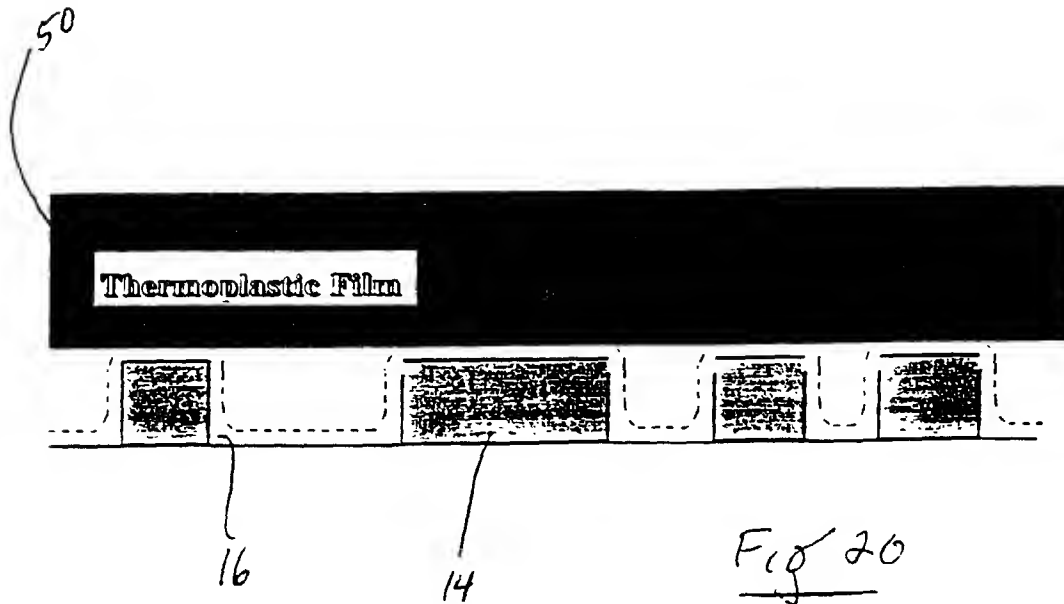


Fig 20

Fig 21

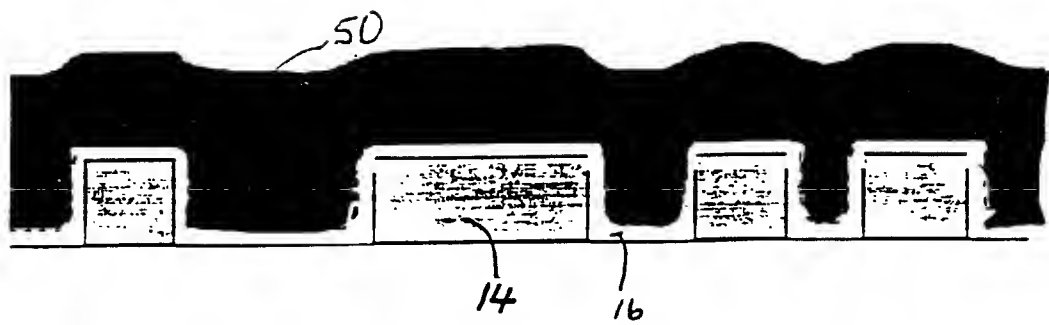
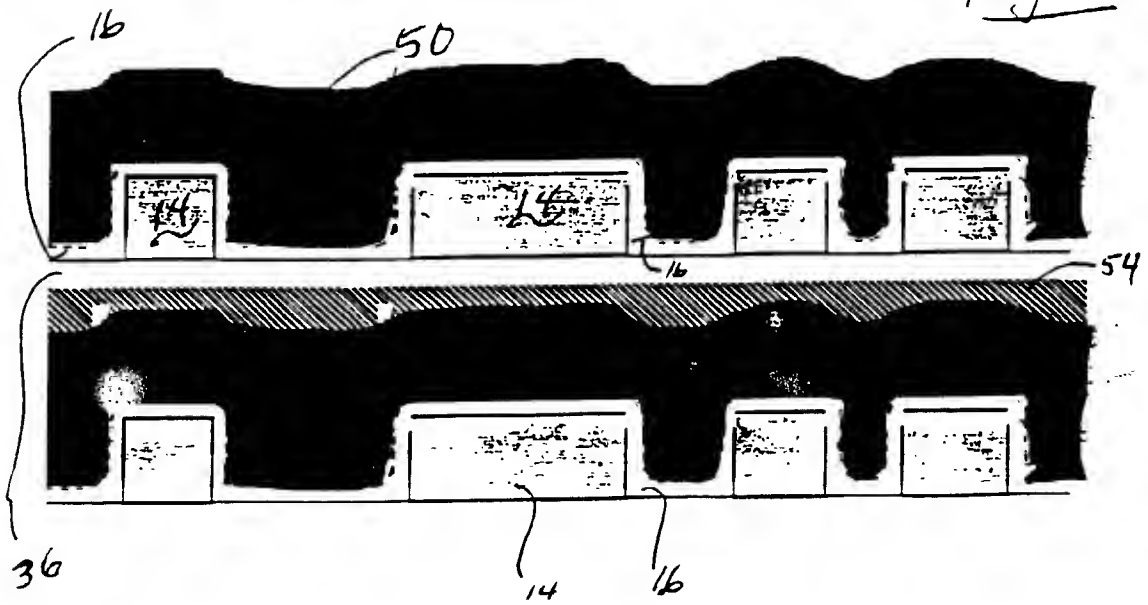
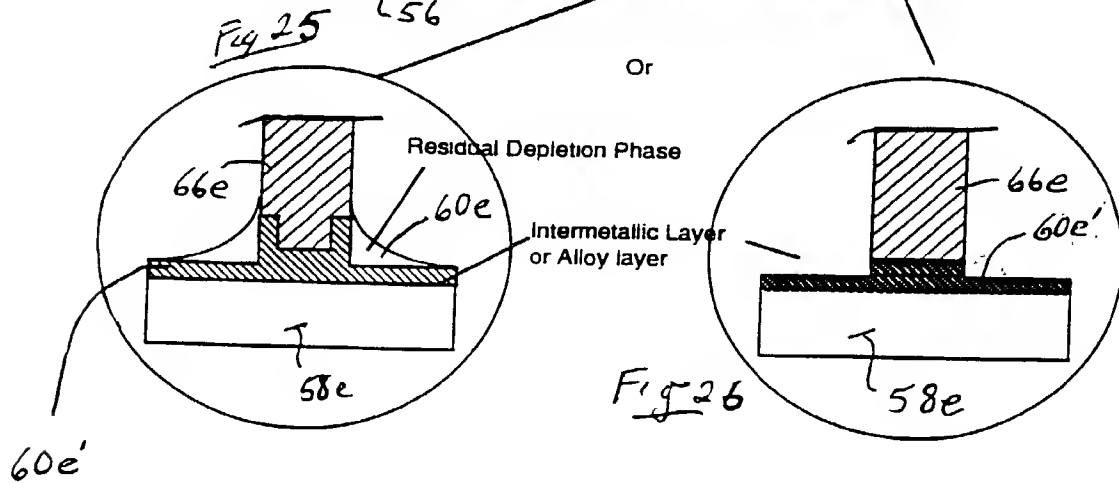


Fig 22





Structure 2

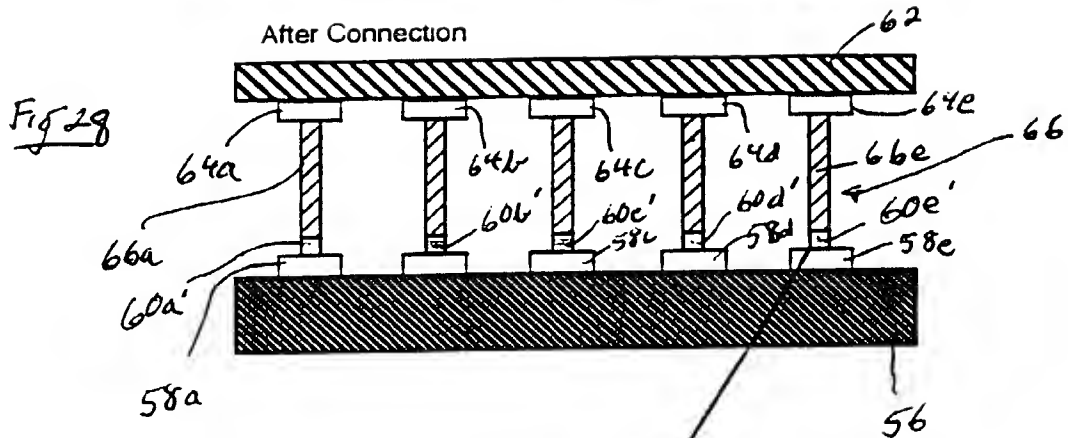
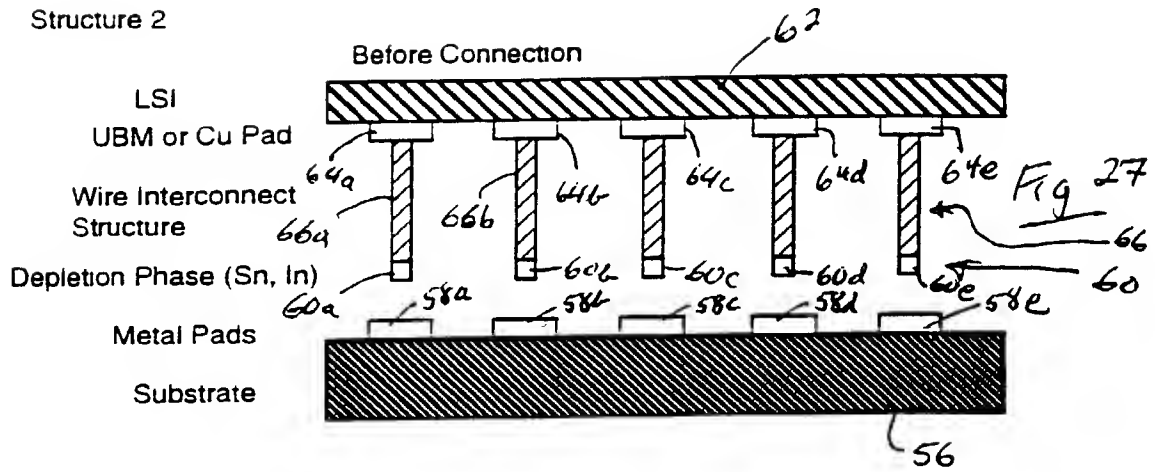
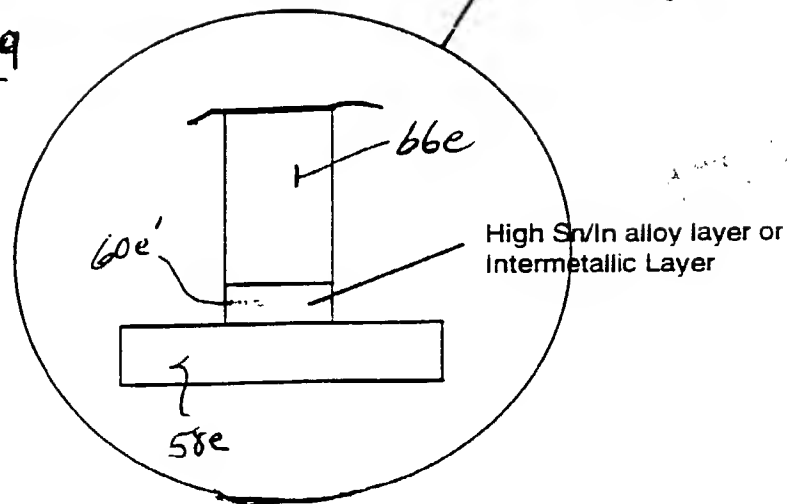
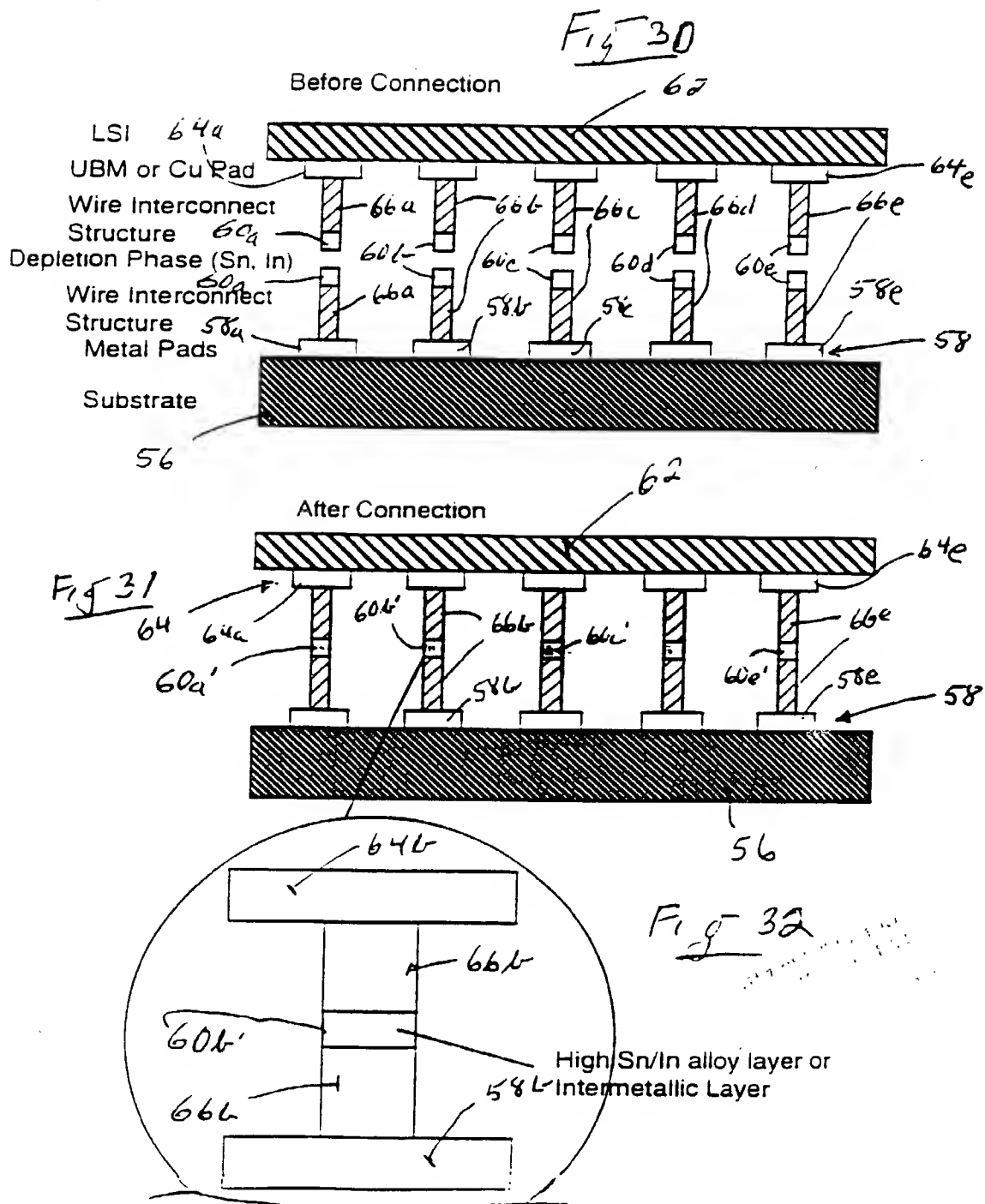
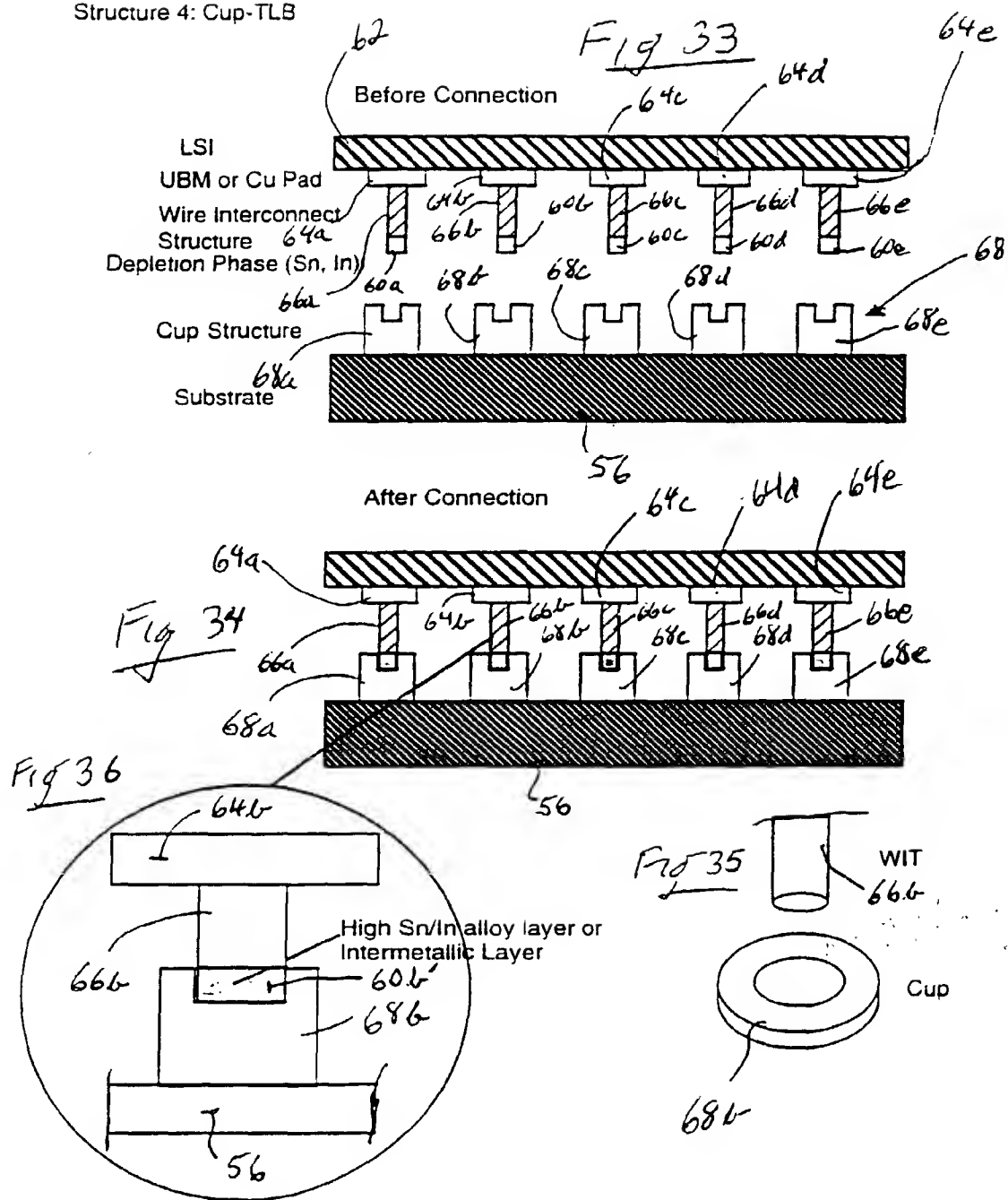


Fig 29



Structure 3



[illegible]

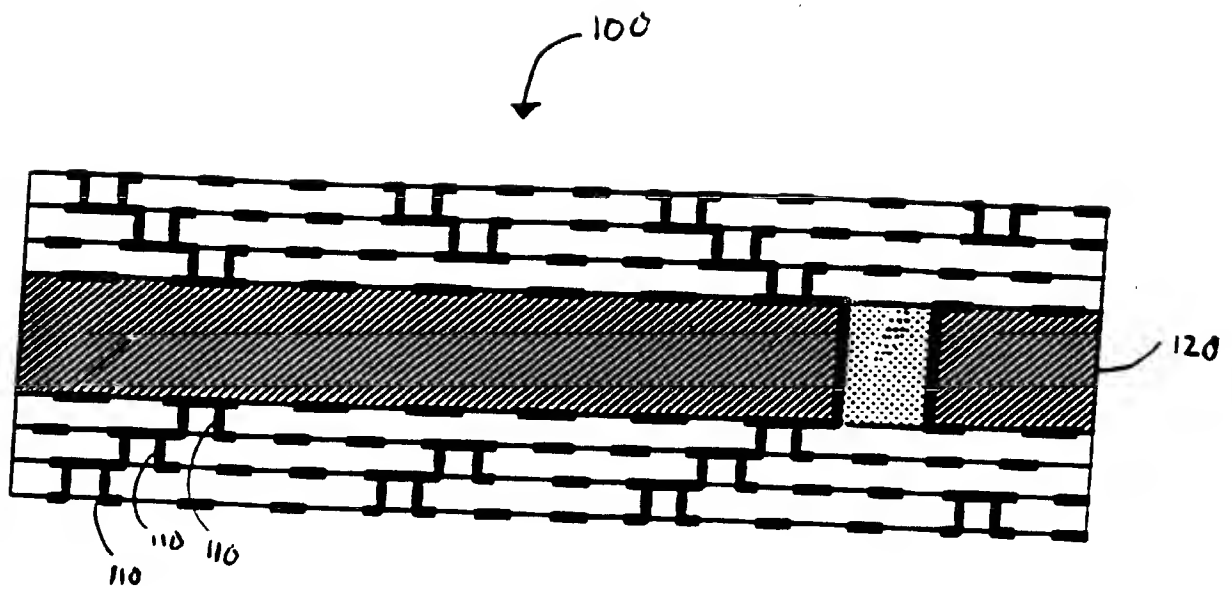
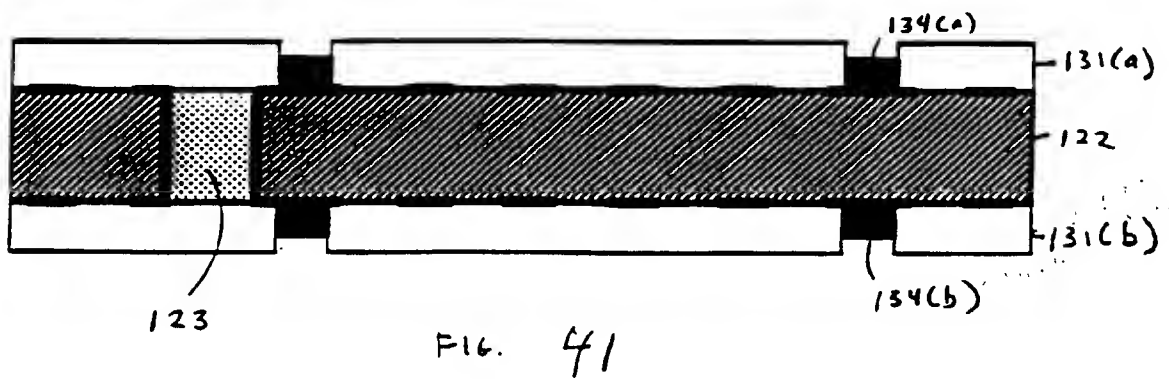
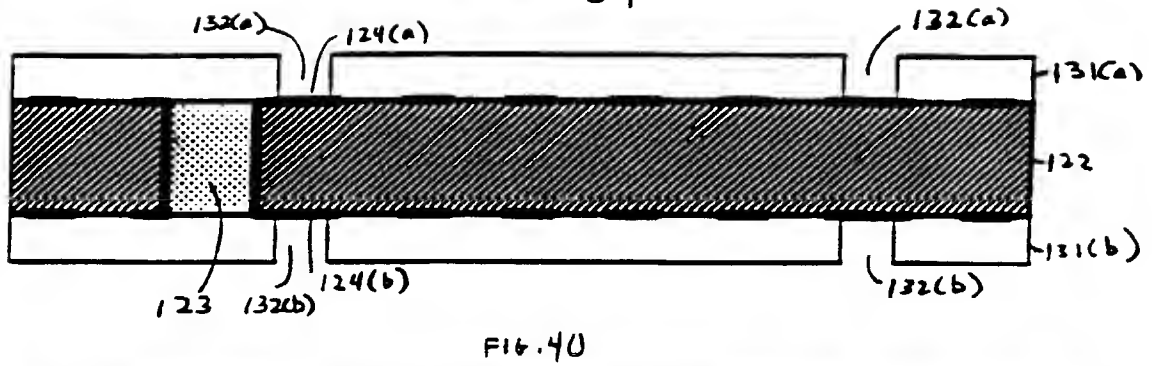
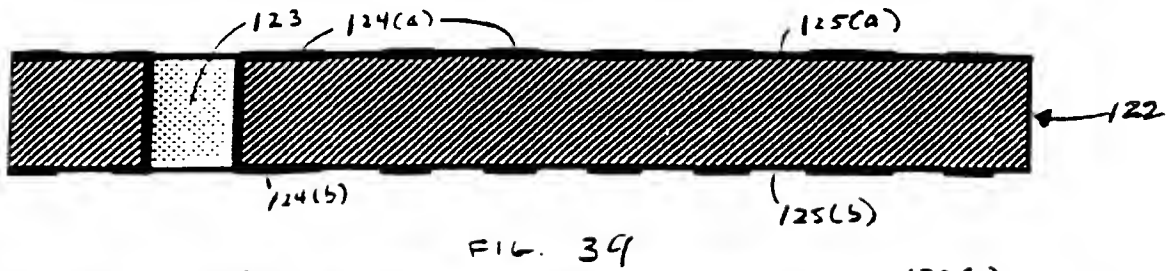
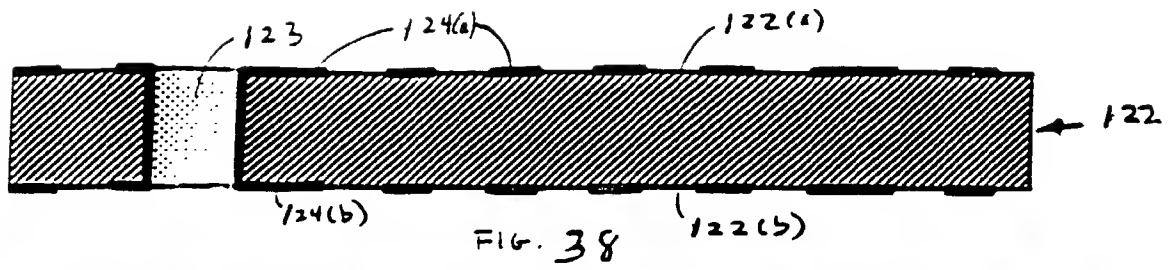
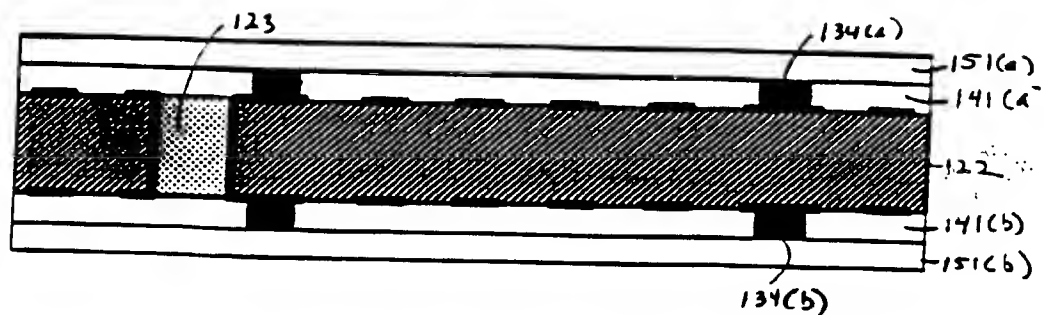
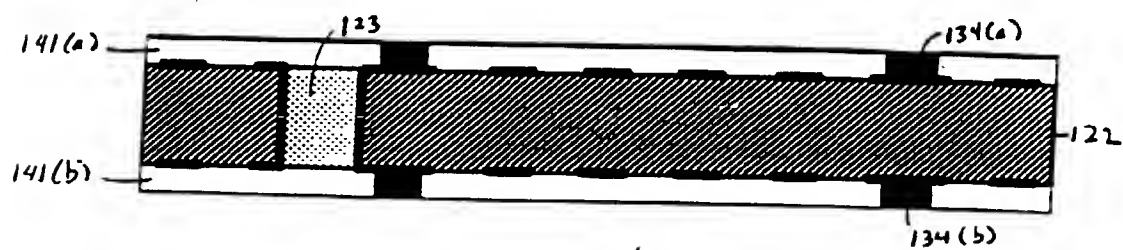
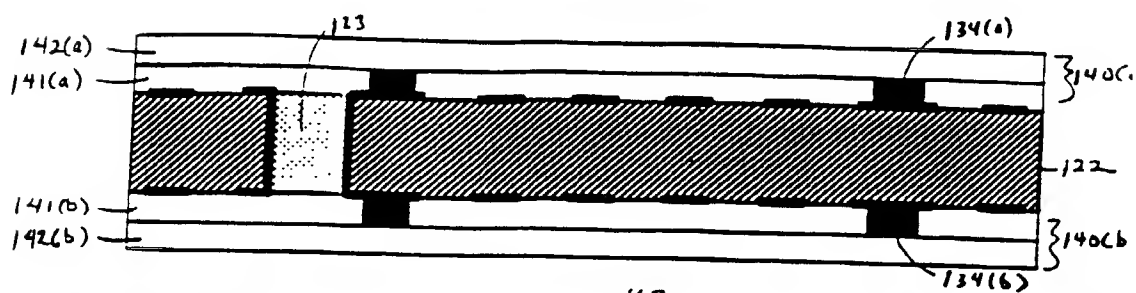
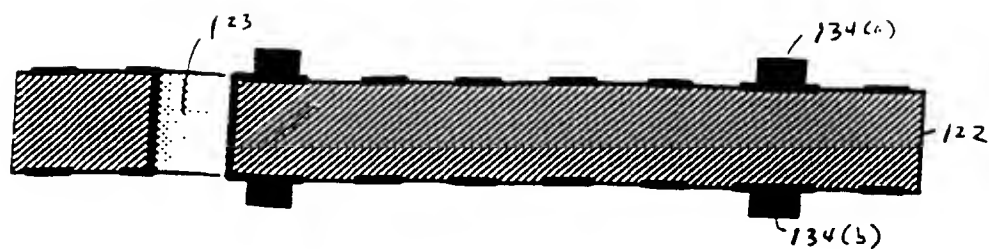


FIG.37



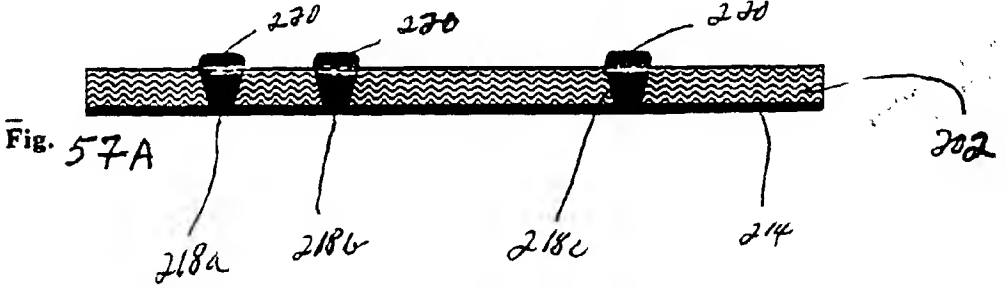
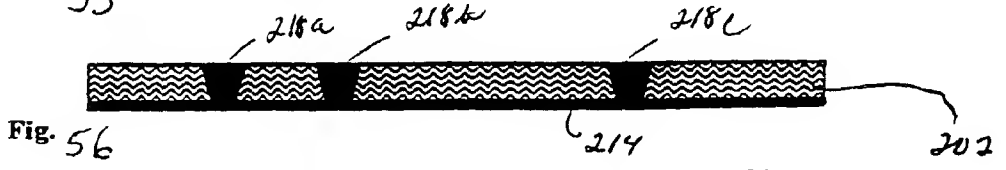
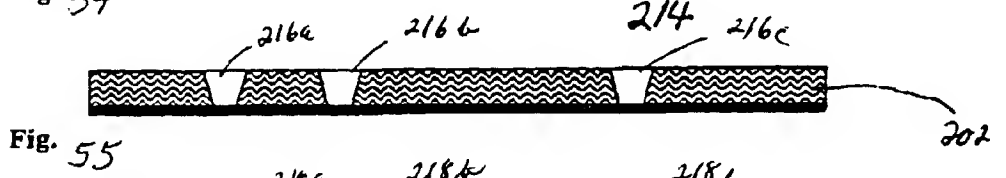
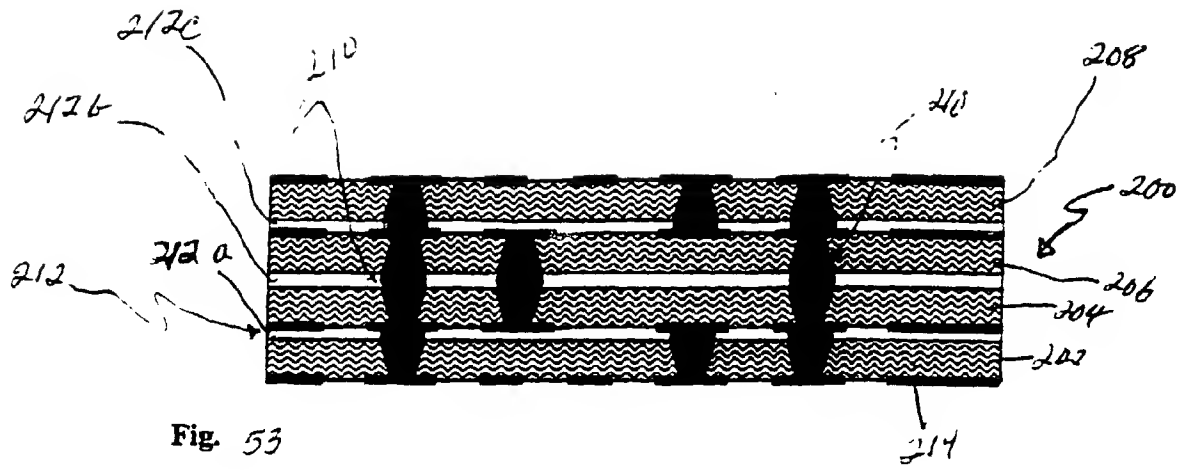


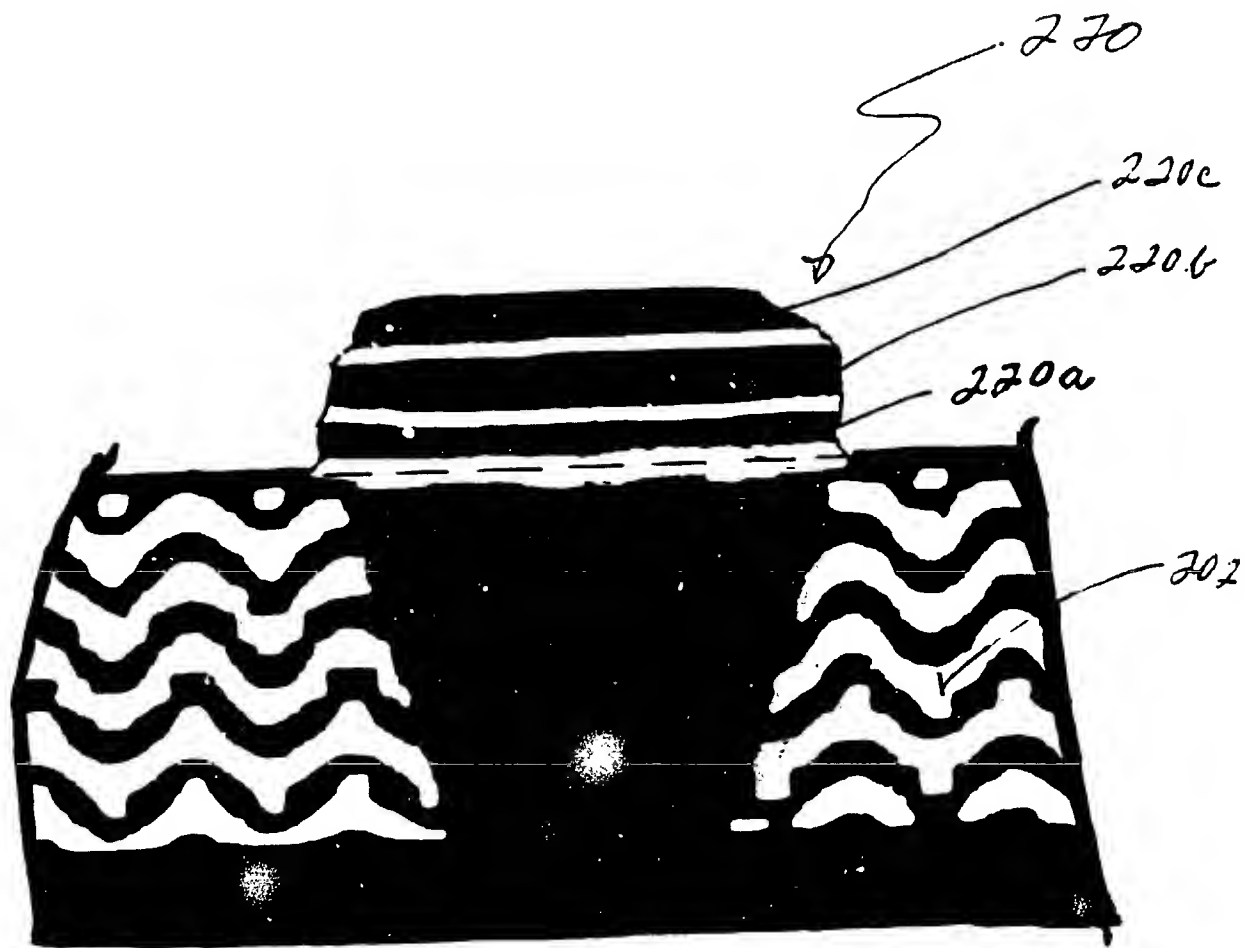












57B











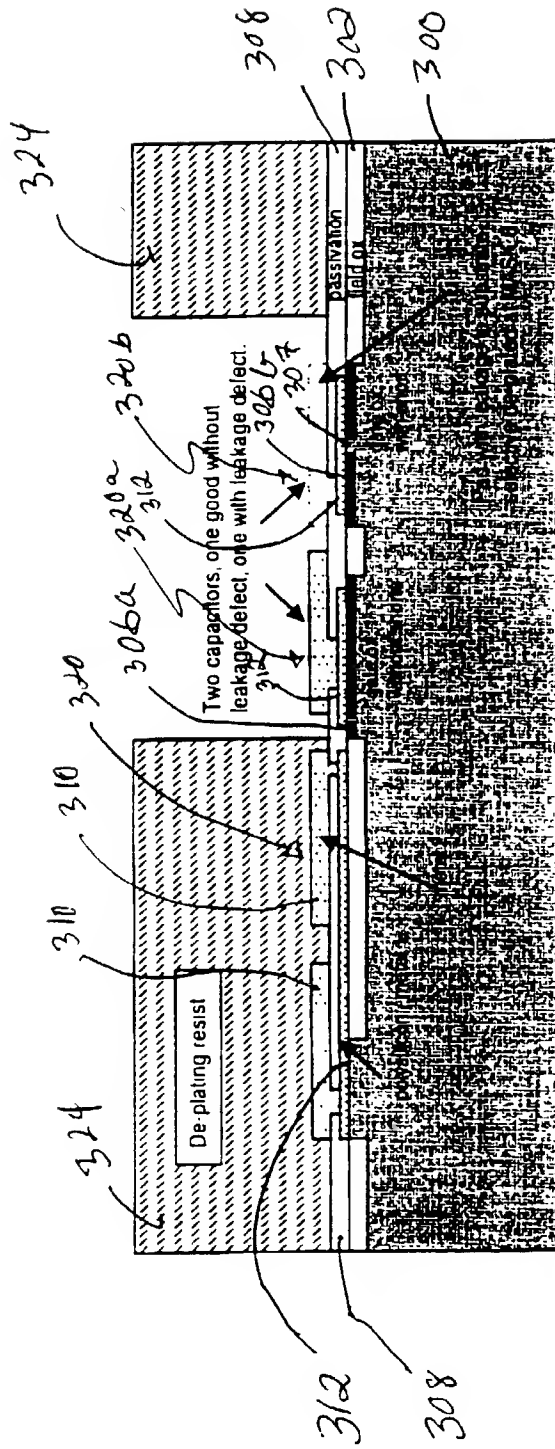


Fig. 66

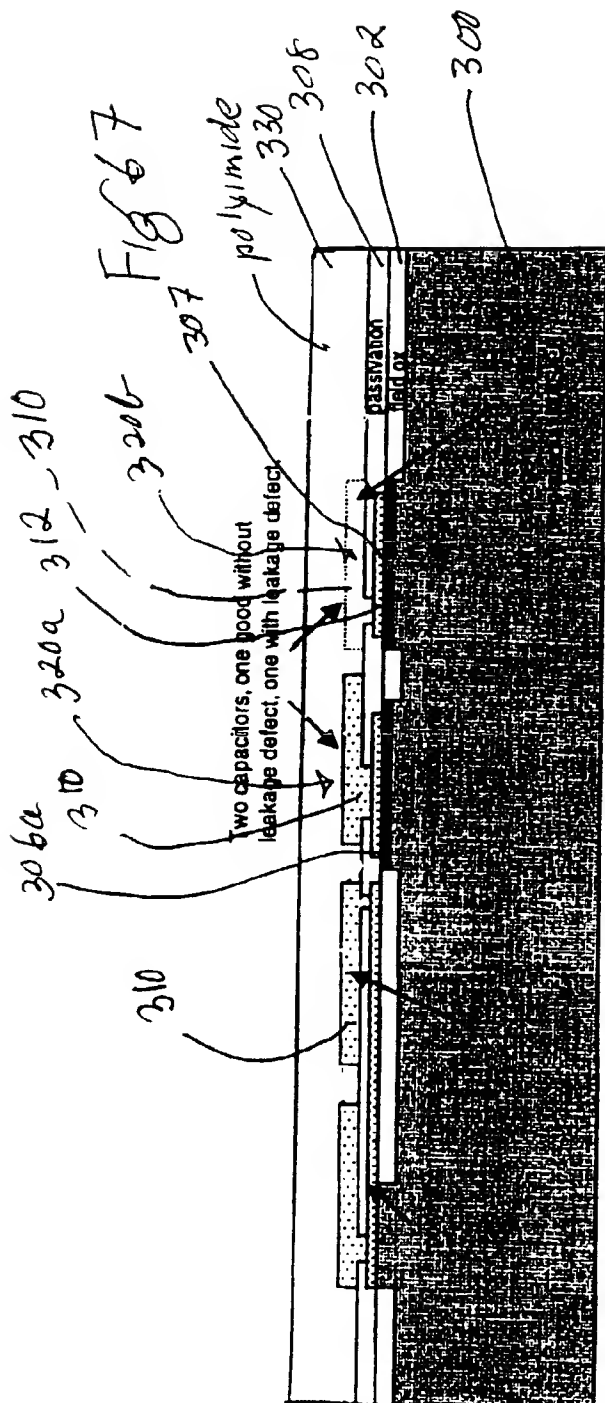


Fig. 67

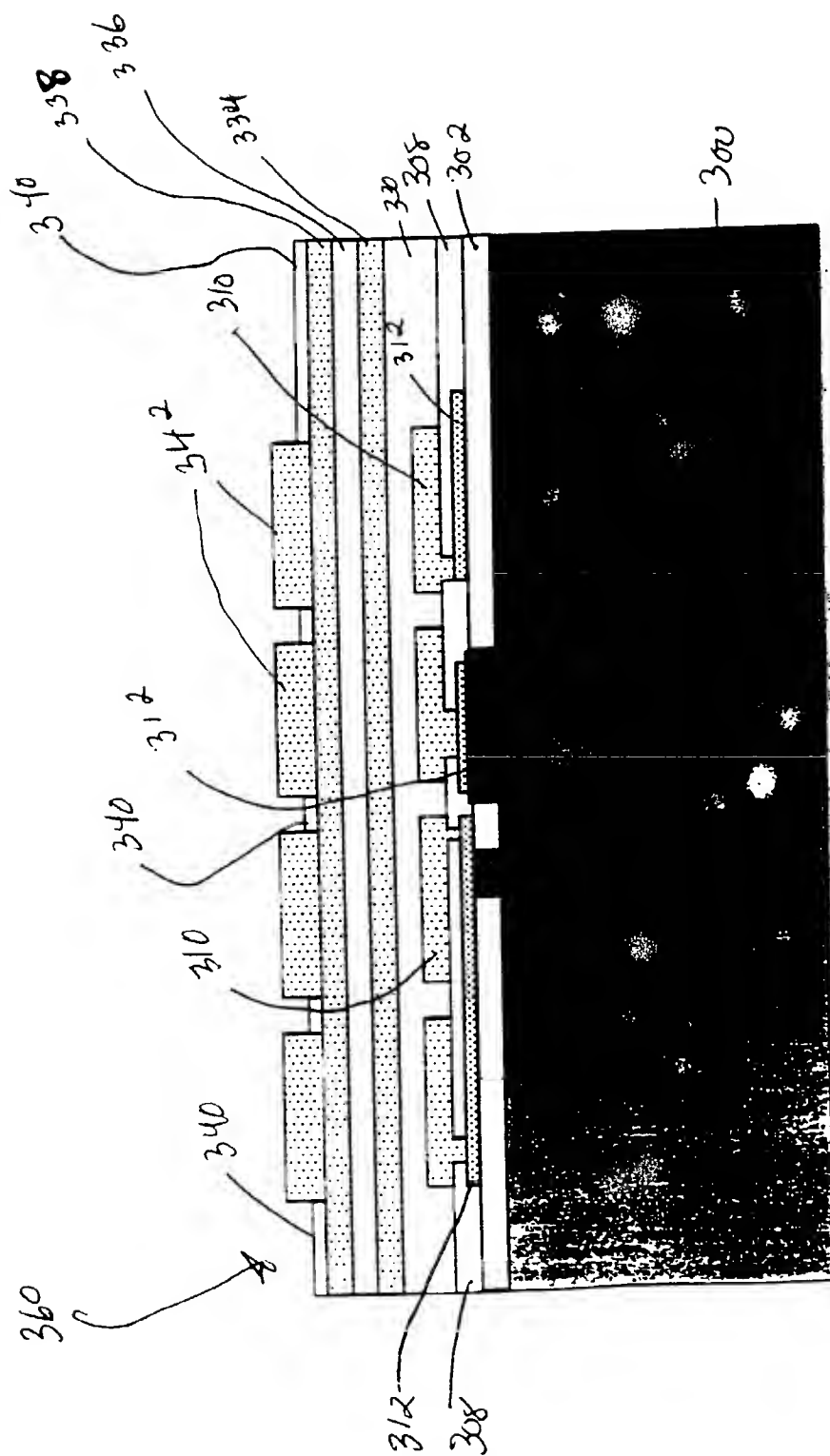


Fig 68

[illegible]

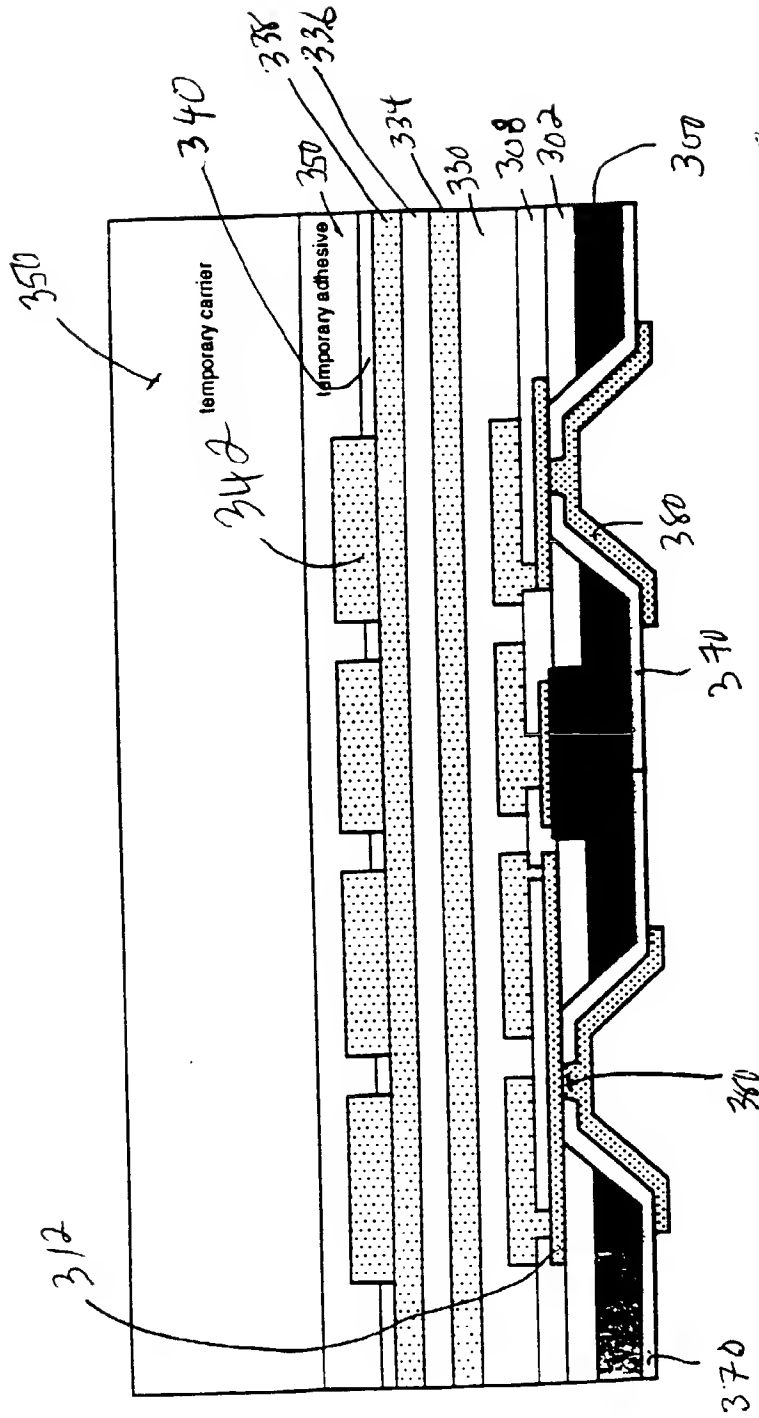


Fig 69



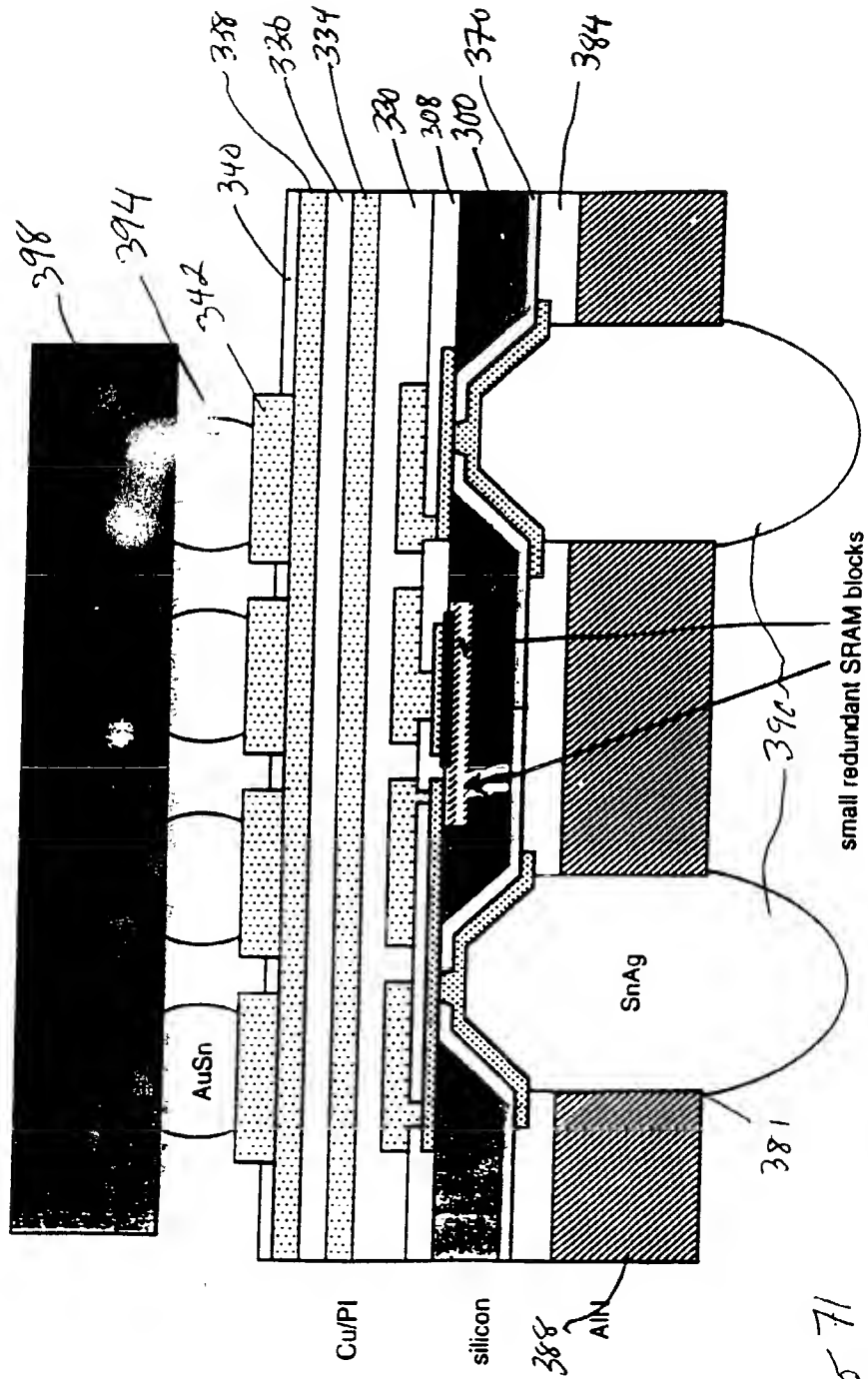
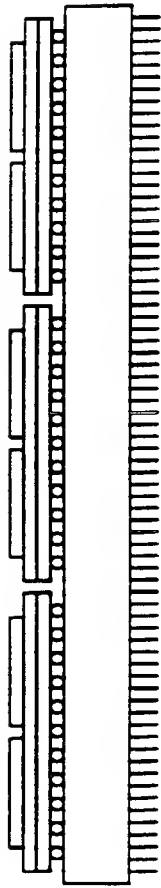


Fig 71

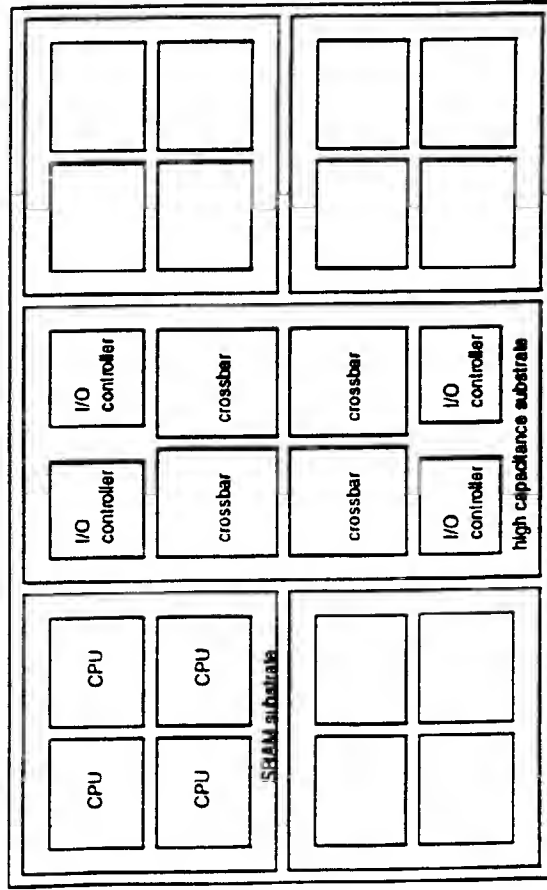




3D SuperChip

Conventional MCM

*Fig 72*

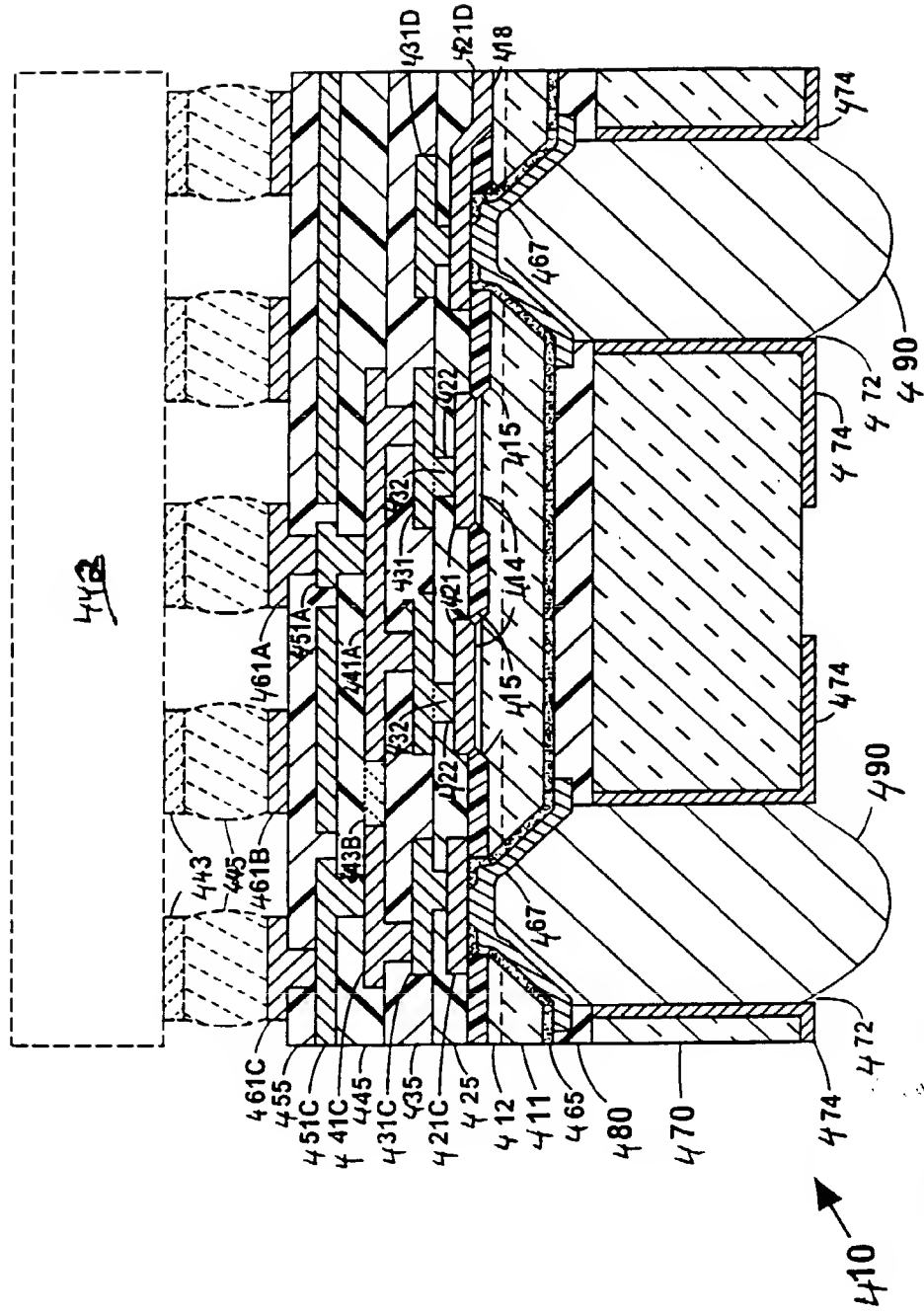


30x40mm  
12 per 6" substrate

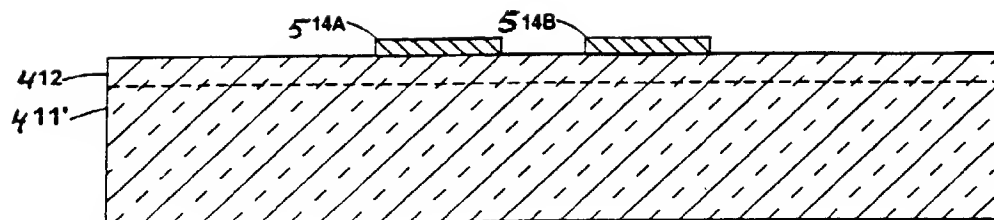
60x120mm  
2 per 6" substrate

*Fig 73*

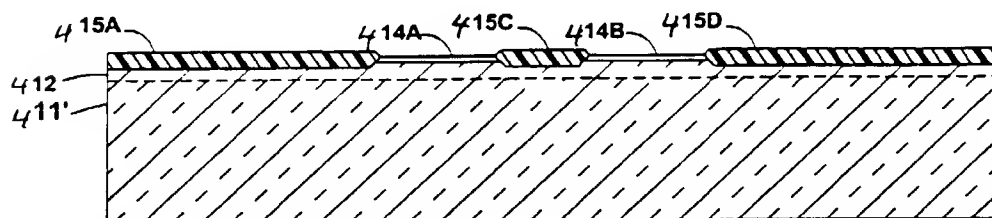




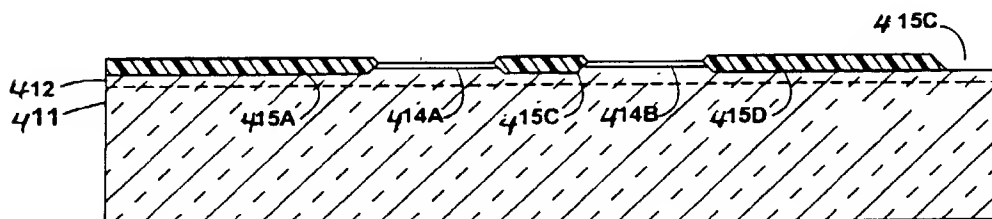
**FIG. 76**



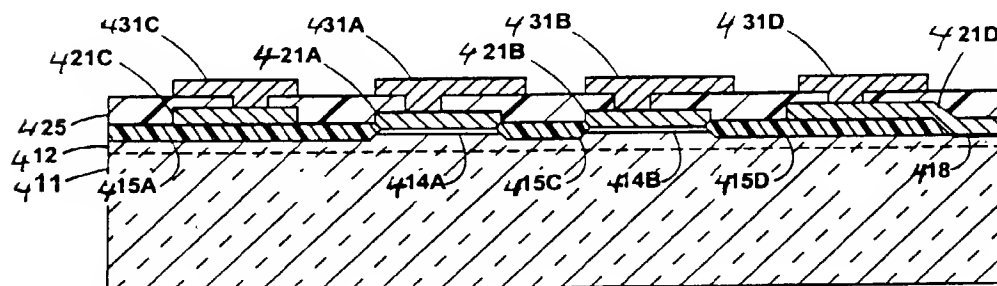
**FIG. 77**



**FIG. 78**



**FIG. 79**



**FIG. 80**

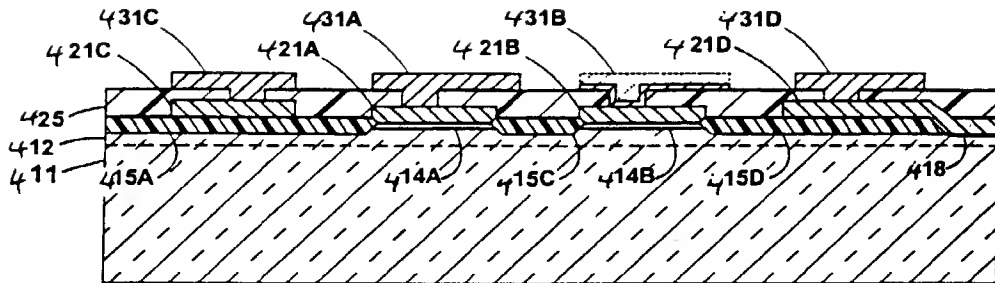


FIG. 81

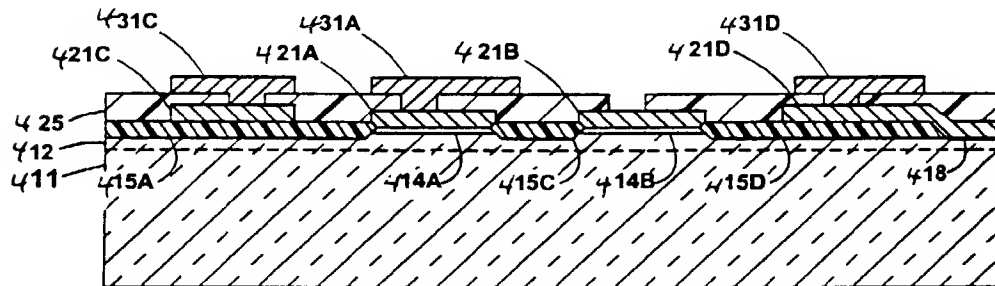


FIG. 82

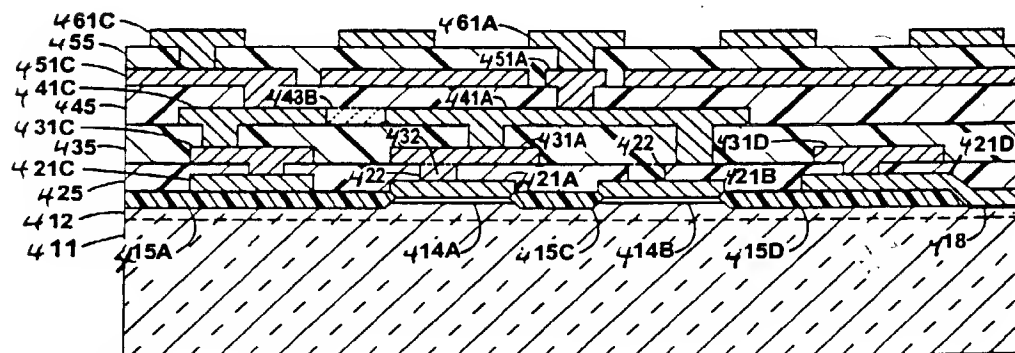
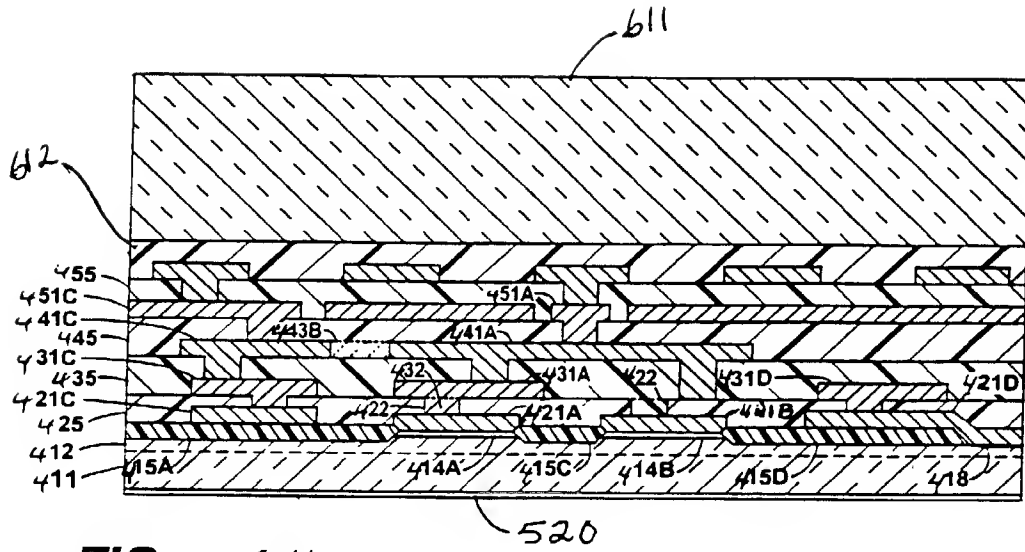
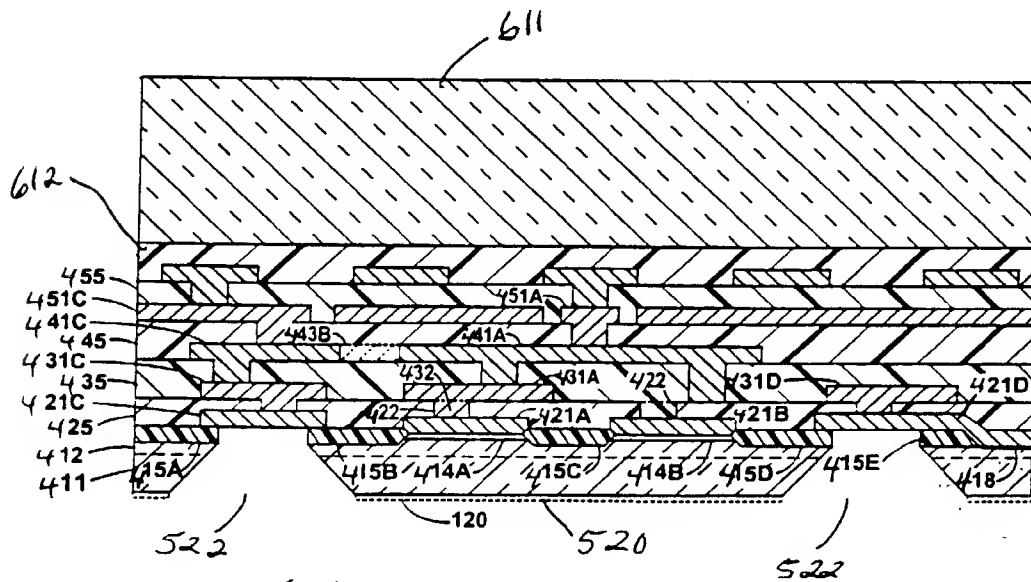


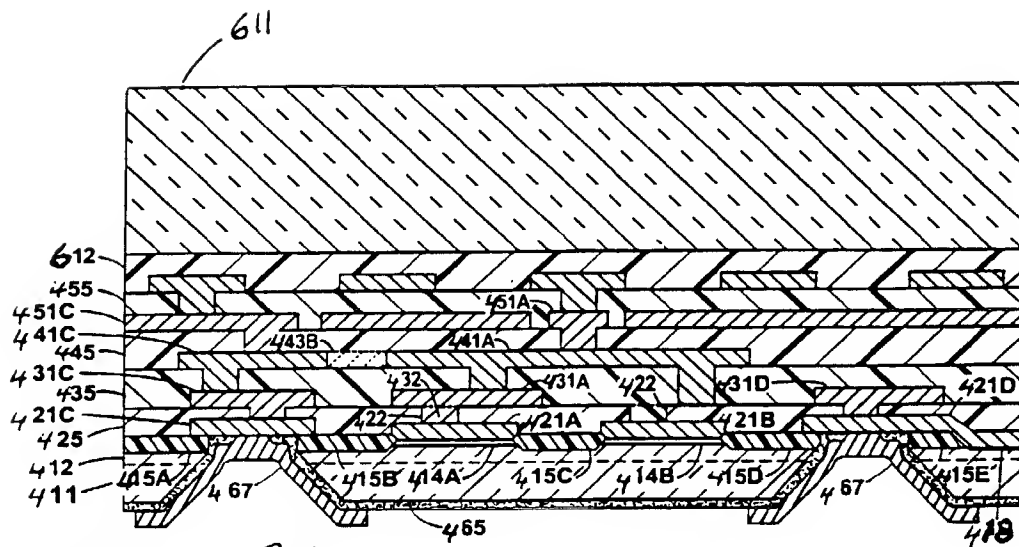
FIG. 83



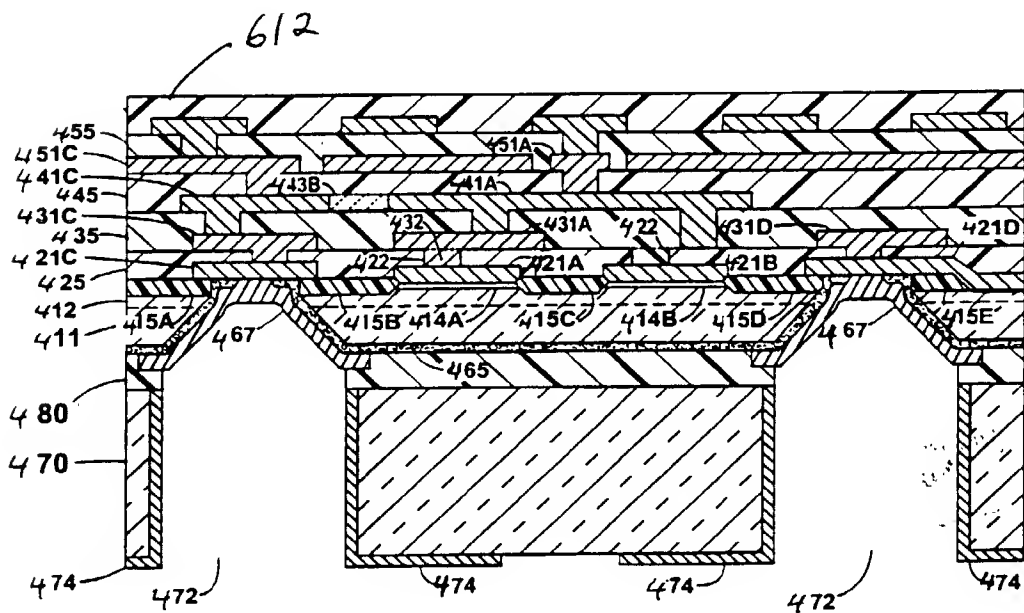
**FIG. 84**



**FIG.** 85



**FIG.** 86



**FIG. 87**